

RKD700KL

Silicon Schottky Barrier Diode for Backflow prevention

REJ03G1337-0100 Rev.1.00 Jan 19, 2006

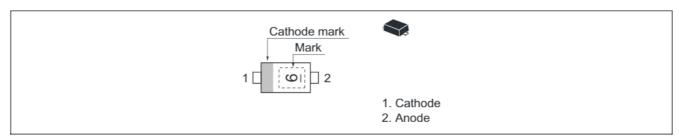
Features

- · Low reverse current, Low capacitance.
- Extremely small Flat Lead Package (EFP) is suitable for surface mount design.

Ordering Information

Type No. Laser Mark		Package Name	Package Code	
RKD700KL	6	EFP	PXSF0002ZA-A	

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit	
Repetitive peak reverse voltage	V _{RRM}	30	V	
Reverse voltage	V _R	30	V	
Non-Repetitive peak forward surge current	I _{FSM} *	200	mA	
Average rectified current	I ₀	50	mA	
Junction temperature	Tj	125	°C	
Storage temperature	Tstg	-55 to +125	°C	

Note: 10 ms Sinewave 1 pulse

Electrical Characteristics

 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V _{F1}	_	0.11	0.14	V	I _F = 1 ∞A
	V _{F2}	_	_	0.33		I _F = 1 mA
	V _{F3}	_	_	0.43		I _F = 10 mA
Reverse current	I _{R1}	_	_	45	nA	V _R = 3 V
	I _{R2}	_	_	1	∞A	V _R = 30 V
Capacitance	С	_	_	2.8	pF	V _R = 1 V, f = 1 MHz

Note: For EFP package, the material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

Main Characteristic

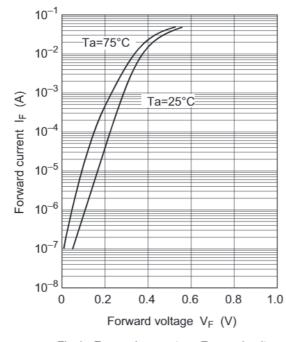
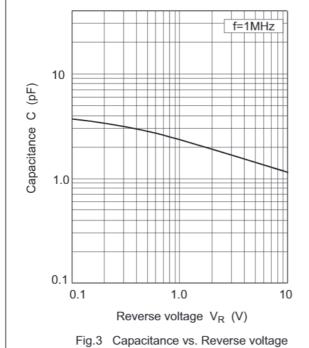


Fig.1 Forward current vs. Forward voltage



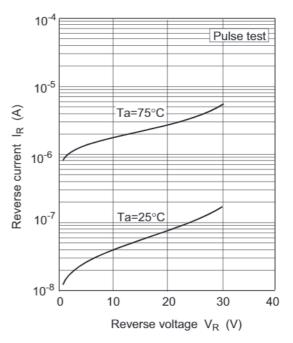
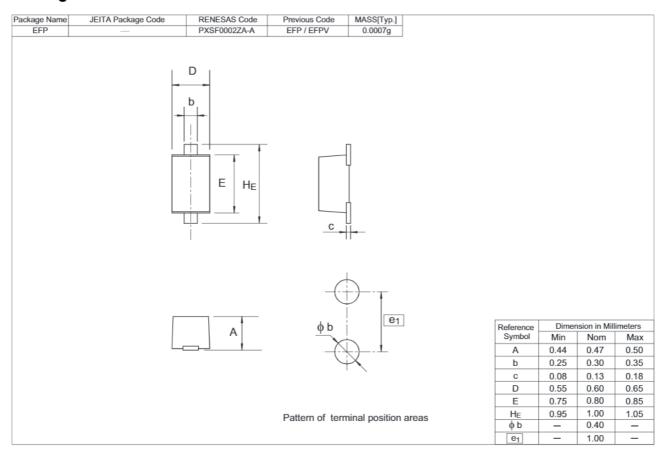


Fig.2 Reverse current vs. Reverse voltage

Package Dimensions



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Renesas Technology Malaysia Sdn. Bhd
Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No.18, Jalan Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia Tel: <603> 7955-9390, Fax: <603> 7955-9510